

PCN Number:	20170721001	PCN Date:	Jul 27, 2017
Title:	Qualification of UMCI as an additional Fab site option for select C014 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Oct 27, 2017	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of UMCI fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
UMC-F12	C014	300 mm	UMCI	C014	300 mm

Passivation differences are noted below:

Change From	Change To
HDP + PSG + PCSiN passivation	PEOX + PSG + HCSiN passivation

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:




Current:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMC-F12	F12	TWN	Tainan

New Fab Site:

New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMCI	UMI	SGP	Singapore

Sample product shipping label (not actual product label)

 <p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:</p> <table border="1"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: 39 ITEM: 39 LBL: 5A (L) TO: 1750</p>	MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04	 	<p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: HYS</p>
MSL 2 / 260C / 1 YEAR	SEAL DT					
MSL 1 / 235C / UNLIM	03/29/04					

Product Affected:

AM3351BZCE30	AM3352BZCZA80	AM3356BZCEA60	AMIC110BZCZA
AM3351BZCE60	AM3352BZCZD30	AM3356BZCZ30	FX053013
AM3351BZCEA30	AM3352BZCZD60	AM3356BZCZ60	SN12065850BZCE
AM3351BZCEA60	AM3352BZCZD80	AM3356BZCZ80	SN12095260BZCE
AM3352BZCE30	AM3352BZCZT60	AM3356BZCZA30	SN13095280BZCZ
AM3352BZCE30R	AM3352BZCZT60R	AM3356BZCZA60	SN13095660BZCZR
AM3352BZCE60	AM3352ZZCZA60	AM3356BZCZA80	SN14015260BZCZ
AM3352BZCEA30	AM3354BZCE60	AM3356BZCZD30	SN14025260BZCZ
AM3352BZCEA30R	AM3354BZCEA60	AM3356BZCZD60	SN14075660BZCZDR
AM3352BZCEA60	AM3354BZCED60	AM3357BZCZA30	SN14085660BZCZDR
AM3352BZCEA60R	AM3354BZCZ100	AM3357BZCZA60	SN15065260BZCZ
AM3352BZCED30	AM3354BZCZ30	AM3357BZCZA80	SN150752100BZCZAR
AM3352BZCED60	AM3354BZCZ60	AM3357BZCZD30	SN15075260BZCZ
AM3352BZCZ100	AM3354BZCZ80	AM3357BZCZD60	SN150952100BZCZ
AM3352BZCZ30	AM3354BZCZA100	AM3358BYS	SN15095260BZCZ
AM3352BZCZ60	AM3354BZCZA60	AM3358BZCZ100	SN15095660BZCZR
AM3352BZCZ80	AM3354BZCZA80	AM3358BZCZ60	SN15125260BZCZD
AM3352BZCZA100	AM3354BZCZA80R	AM3358BZCZ80	SN16085660BZCZAR
AM3352BZCZA100R	AM3354BZCZD60	AM3358BZCZA100	SN278792960
AM3352BZCZA30	AM3354BZCZD80	AM3358BZCZA80	SUBARCTICBDEVZCZ
AM3352BZCZA60	AM3354BZCZD80R	AM3359BZCZA80	TNETV2241BZCZ

Qualification Report**Qualification of UMCi as Second Source Fab Site for AM335xB**

Approved 7/19/17

Product Attributes

Attributes	Qual Device: XDRA618BIZCZ (1)
Assembly Site	PHI
Package Family	NFBGA
Wafer Fab Supplier	UMCi
Wafer Fab Process	C014.M

- Qual Device XDRA618BIZCZ is qualified at LEVEL3-260CP

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: XDRA618BIZCZ (1)
HTOL	Life Test, 135C Tj	1000 Hours	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/231/0
TC	Temperature Cycle, -55/125C	1000 Cycles	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	3/231/0
UHAST	Unbiased HAST 110C/85%RH	96 Hours	3/231/0
CDM	ESD - CDM	500 V	1/5/0
HBM	ESD - HBM	2000 V	1/5/0
LU	Latch-up	+/- 45 mA and 1.5 x Vmax @ max Tj	1/6/0

- (1) XDRA618BIZCZ is the automotive version of the AM335x device family and is functionally equivalent

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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